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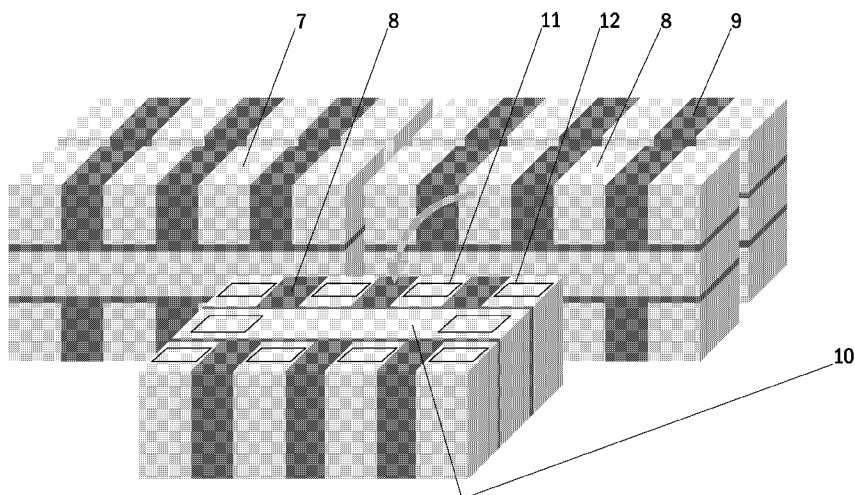
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(54) Title: METHOD FOR MANUFACTURING A MICROMECHANICAL MOTION SENSOR, AND A MICROMECHANICAL MOTION SENSOR



(57) Abstract: The present invention relates to measuring devices used in measuring physical quantities, such as acceleration, angular acceleration, or angular velocity, and, more precisely, to micromechanical motion sensors. The area, in the wafer plane, of a motion sensor component according to the present invention is smaller than the area of the motion sensor component having been dice cut and turned by 90°. Correspondingly, the height of the motion sensor component according to the present invention, the component having been turned by 90°, is smaller, in the direction of the joint, than the thickness of the wafer stack formed by the joined wafers. The object of the invention is to provide an improved method of manufacturing a micromechanical motion sensor, and to provide a micromechanical motion sensor suitable, in particular, for use in small micromechanical motion sensor solutions.

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